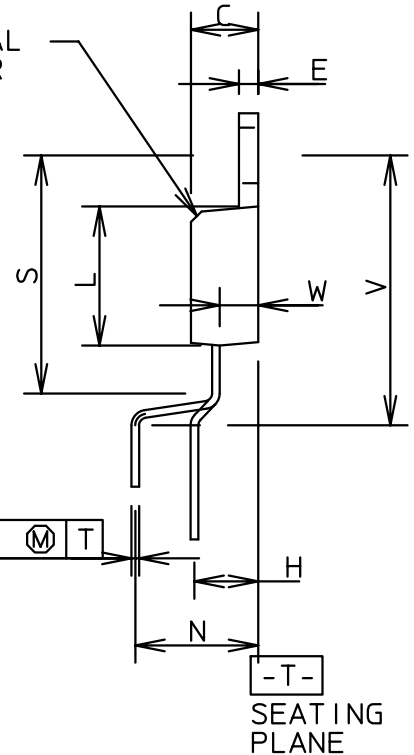


OPTIONAL
CHAMFER



5X D
 Φ .010(.254) (M) T P (M)

5X J
 Φ .024(.610) (M) T

-T-
SEATING
PLANE

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	14.529	15.570	0.572	0.613
B	9.906	10.541	0.390	0.415
C	4.318	4.572	0.170	0.180
D	0.635	0.965	0.025	0.038
E	1.219	1.397	0.048	0.055
F	21.590	23.749	0.850	0.935
G	1.702	BSC	0.067	BSC
H	4.216	BSC	0.166	BSC
J	0.381	0.635	0.015	0.025
K	22.860	27.940	0.900	1.100
L	8.128	9.271	0.320	0.365
N	8.128	BSC	0.320	BSC
Q	3.556	3.886	0.140	0.153
S	-----	15.748	-----	0.620
U	11.888	12.827	0.468	0.505
V	-----	18.669	-----	0.735
W	2.286	2.794	0.090	0.110

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION INCH
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAM BAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043(1.092) MAXIMUM.
 4. 314B-01, 314B-02, 314B-03, 314-04 OBSOLETE, NEW STANDARD 314B-05.
 5. STYLE 1 THRU 4 OBSOLETE
- STYLE 5:
PIN 1. GATE
2. MIRROR
3. DRAIN
4. KELVIN
5. SOURCE

CASE NO.	314B-05
STANDARD	ON SEMI STANDARD
REFERENCE	Q
TITLE	5LD TO-220 SMART MOS

ON Semiconductor	Document Number: 98ASB42218B	Issue: L
	Page 2 of 2	

Revision History

Revision/ Date	Description of Revision & Writer	DDCM Coord	Effectivity Date
L 30 May 2003	Changed ownership from Motorola to On Semiconductor. Requested by Mary Ellington.	M. Ellington	30 May 2003